Under Development

TOSHIBA Field Effect Transistor
Silicon N Channel MOS Type (Lateral)

S S M 3 K 1 1 T

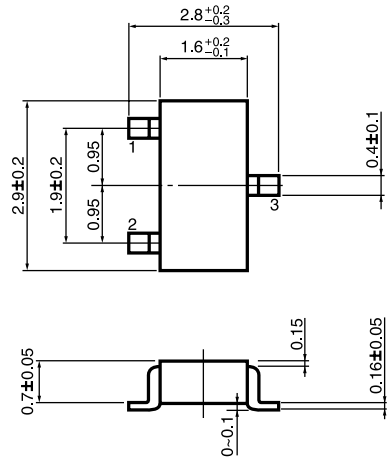
The information contained herein in subject to change without notice; likewise, product development may be discontinued.

DC-DC Converter

High Speed Switching Applications

- Ultra-high-speed switching achieved using a lateral structure
  t_{on} = 6.4 ns, t_{off} = 4.9 ns
- Low reverse transfer capacitance: C_{rss} = 6.8 pF (typ.)
- Thin package
- Low ON-resistance: $R_{DS\ (ON)}$ = 1.2 Ω (typ.) @V_{GS} = 2.5 V
- Direct drive by CMOS possible

Unit in: mm



1.GATE
2.DRAIN
3.SOURCE

TSM	
JEDEC	TO-236MOD
EIAJ	SC-59
TOSHIBA	2-3S1B

Weight: 10 mg

Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit
Drain-Source voltage		V_{DS}	40	V
Gate-Source voltage		V_{GSS}	±10	V
Drain current	DC	I_D	500	mA
	Pulse	I_{DP} (Note2)	2	A
Drain power dissipation		P_D (Note1)	1250	mW
Channel temperature		T_{ch}	150	°C
Storage temperature range		T_{stg}	−55~150	°C

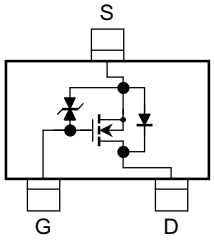
Note1: Mounted on FR4 board
(25.4 mm × 25.4 mm × 1.6 t, Cu pad: 645 mm^2, t = 10 s)

Note2: The pulse width limited by max channel temperature.

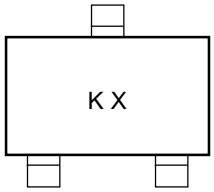
Handling Precaution

The Channel-to-Ambient thermal resistance $R_{th\ (ch\text{-}a)}$ and the drain power dissipation P_D vary according to the board material, board area, board thickness and pad area, and are also affected by the environment in which the product is used. When using this device, please take heat dissipation fully into account.

Equivalent Circuit



Marking



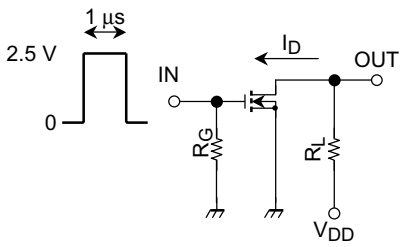
Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		I_{GSS}	V_{GS} = ±10 V, V_{DS} = 0	—	—	±0.1	μA
Drain-Source breakdown voltage		$V_{(BR)\ DSS}$	I_D = 1 mA, V_{GS} = 0	40	—	—	V
Drain Cut-off current		I_{DSS}	V_{DS} = 40 V, V_{GS} = 0	—	—	1	μA
Gate threshold voltage		V_{th}	V_{DS} = 3 V, I_D = 0.1 mA	0.8	—	1.4	V
Forward transfer admittance		$\|Y_{fs}\|$	V_{DS} = 3 V, I_D = 500 mA (Note3)	0.55	1.1	—	S
Drain-Source ON resistance		$R_{DS\ (ON)}$	I_D = 250 mA, V_{GS} = 2.5 V (Note3)	—	1.2	1.8	Ω
			I_D = 500 mA, V_{GS} = 4 V (Note3)	—	1.0	1.3	
Input capacitance		C_{iss}	V_{DS} = 3 V, V_{GS} = 0, f = 1 MHz	—	64	—	pF
Reverse transfer capacitance		C_{rss}	V_{DS} = 3 V, V_{GS} = 0, f = 1 MHz	—	6.8	—	pF
Output capacitance		C_{oss}	V_{DS} = 3 V, V_{GS} = 0, f = 1 MHz	—	38	—	pF
Switching time	Rise time	t_r	V_{DD} = 10 V, I_D = 250 mA, V_{GS} = 0~2.5 V	—	2.9	—	ns
	Turn-on time	t_{on}		—	6.4	—	
	Fall time	t_f		—	2.1	—	
	Turn-off time	t_{off}		—	4.9	—	

Note3: Pulse test

Switching Time Test Circuit

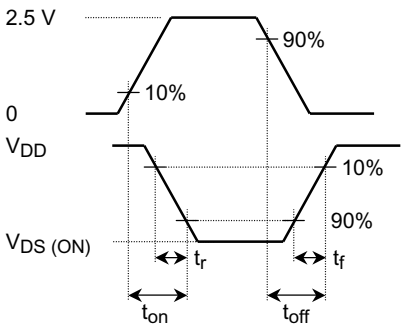
(a) Test circuit



V_{DD} = 10 V
R_G = 50 Ω
D.U. ≦ 1%
V_{IN}: t_r, t_f < 5 ns
Common source
Ta = 25°C

(b) V_{IN}

(c) V_{OUT}



Precaution

V_{th} can be expressed as voltage between gate and source when low operating current value is I_D = 100 μA for this product. For normal switching operation, $V_{GS\ (on)}$ requires higher voltage than V_{th} and $V_{GS\ (off)}$ requires lower voltage than V_{th}.

(relationship can be established as follows: $V_{GS\ (off)} < V_{th} < V_{GS\ (on)}$)

Please take this into consideration for using the device.

V_{GS} recommended voltage of 2.5 V or higher to turn on this product.